

IGBT XPT Module

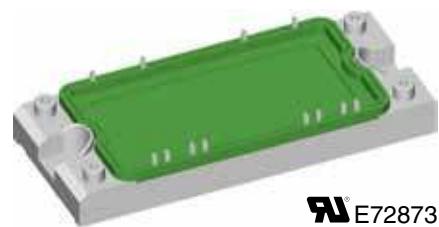
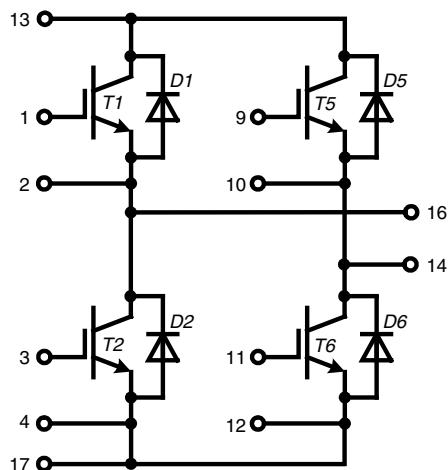
H Bridge

$V_{CES} = 1200 \text{ V}$
 $I_{C25} = 85 \text{ A}$
 $V_{CE(sat)} = 1.8 \text{ V}$

Preliminary data

Part name (Marking on product)

MIXA 61H1200ED



UL E72873

Features:

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design
(Xtreme light Punch Through) results in:
 - short circuit rated for 10 μsec .
 - very low gate charge
 - square RBSOA @ 3x I_C
 - low EMI
- Thin wafer technology combined with the XPT design results in a competitive low $V_{CE(sat)}$
- SONIC™ diode
 - fast and soft reverse recovery
 - low operating forward voltage

Application:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies

Package:

- "E2-Pack" standard outline
- Insulated copper base plate
- Soldering pins for PCB mounting

Output Inverter T1 - T6

Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$		1200		V
V_{GES}	max. DC gate voltage	continuous		± 20		V
V_{GEM}	max. transient collector gate voltage	transient		± 30		V
I_{C25}	collector current	$T_C = 25^\circ C$	85		A	
I_{C80}		$T_C = 80^\circ C$	60		A	
P_{tot}	total power dissipation	$T_C = 25^\circ C$	290		W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 55 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.8 2.1	2.1	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 2 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.4	6.0	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	0.2	0.5	mA
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$		500	nA	
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_C = 50 A$	165		nC	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	turn-on delay time current rise time turn-off delay time current fall time turn-on energy per pulse turn-off energy per pulse	inductive load $V_{CE} = 600 V; I_C = 50 A$ $V_{GE} = \pm 15 V; R_G = 15 \Omega$	$T_{VJ} = 125^\circ C$	70 40 250 100 4.5 5.5		ns ns ns ns mJ mJ
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 15 \Omega;$	$T_{VJ} = 125^\circ C$ $V_{CEK} = 1200 V$		150	A
SCSOA	short circuit safe operating area					
t_{sc} I_{sc}	short circuit duration short circuit current	$V_{CE} = 900 V; V_{GE} = \pm 15 V;$ $R_G = 15 \Omega$; non-repetitive	$T_{VJ} = 125^\circ C$	200	10	μs
R_{thJC}	thermal resistance junction to case	(per IGBT)			0.43	K/W

Output Inverter D1 - D6

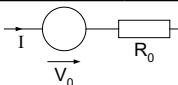
Ratings

Symbol	Definitions	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1200		V
I_{F25}	forward current	$T_C = 25^\circ C$	85		A	
I_{F80}		$T_C = 80^\circ C$	57		A	
V_F	forward voltage	$I_F = 60 A; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$	1.95 1.95	2.2	V
Q_{rr} I_{RM} t_{rr} E_{rec}	reverse recovery charge max. reverse recovery current reverse recovery time reverse recovery energy	$V_R = 600 V$ $di_F/dt = -1200 A/\mu s$ $I_F = 60 A; V_{GE} = 0 V$	$T_{VJ} = 125^\circ C$	8 60 350 2.5		μC A ns mJ
R_{thJC}	thermal resistance junction to case	(per diode)			0.6	K/W

 $T_C = 25^\circ C$ unless otherwise stated

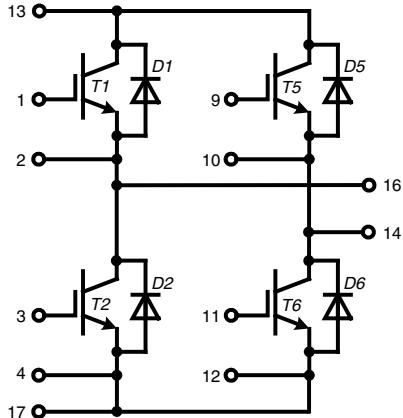
Module

Symbol	Definitions	Conditions	Ratings		
			min.	typ.	max.
T_{VJ}	<i>operating temperature</i>		-40		125
T_{VJM}	<i>max. virtual junction temperature</i>				150
T_{stg}	<i>storage temperature</i>		-40		125
V_{ISOL}	<i>isolation voltage</i>	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$			3000
CTI	<i>comparative tracking index</i>				-
M_d	<i>mounting torque (M5)</i>		3		6
d_s	<i>creep distance on surface</i>		6		mm
d_A	<i>strike distance through air</i>		6		mm
$R_{pin-chip}$	<i>resistance pin to chip</i>			5	$\text{m}\Omega$
R_{thCH}	<i>thermal resistance case to heatsink</i>	with heatsink compound		0.02	K/W
Weight				180	g

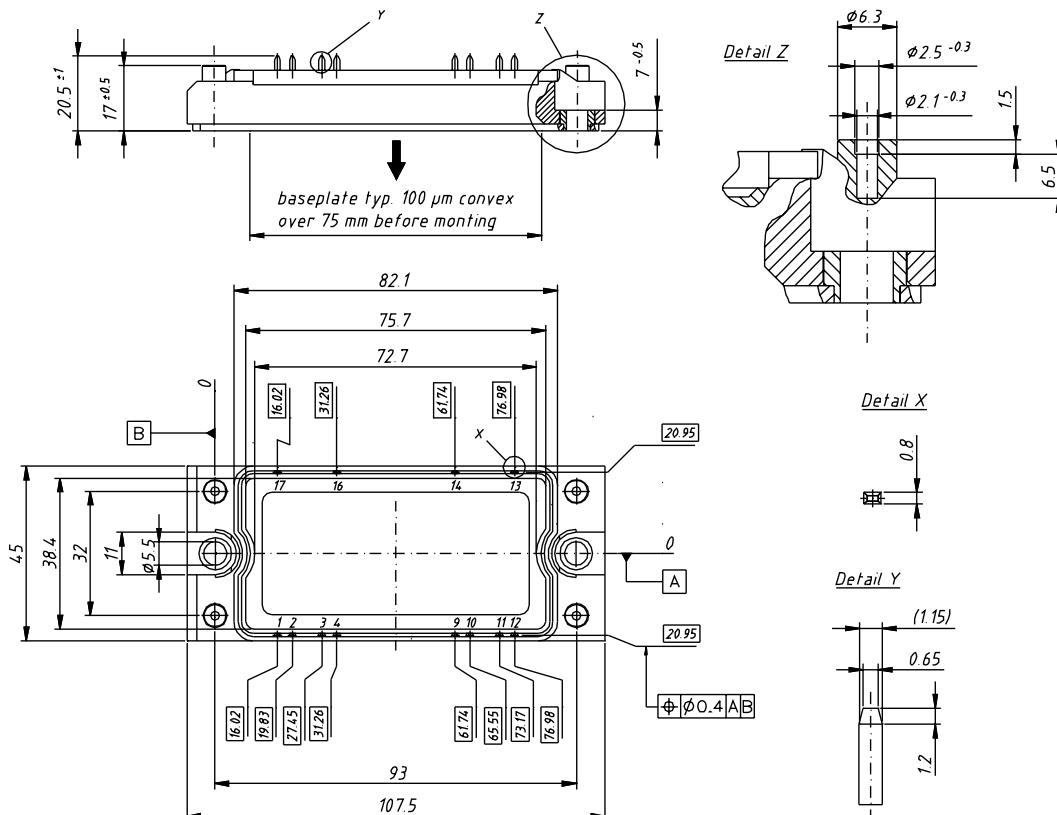
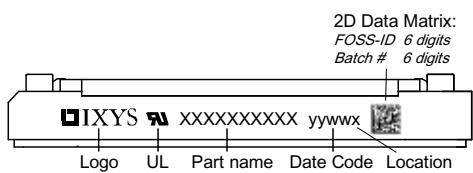
Equivalent Circuits for Simulation

Symbol	Definitions	Conditions	Ratings		
			min.	typ.	max.
V_0	<i>IGBT</i>	T1 - T6	$T_{VJ} = 150^\circ\text{C}$	1.1	
R_0				25.1	$\text{m}\Omega$
V_0	<i>free wheeling diode</i>	D1 - D6	$T_{VJ} = 150^\circ\text{C}$	1.22	
R_0				12.99	$\text{m}\Omega$

$T_c = 25^\circ\text{C}$ unless otherwise stated

Circuit Diagram**Outline Drawing**

Dimensions in mm (1 mm = 0.0394")

**Product Marking****Part number**

M = Module
 I = IGBT
 X = XPT
 A = standard
 61 = Current Rating [A]
 H = H~ Bridge
 1200 = Reverse Voltage [V]
 ED = E2-Pack

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MIXA61H1200ED	MIXA61H1200ED	Box	6	511060

IXYS reserves the right to change limits, test conditions and dimensions.

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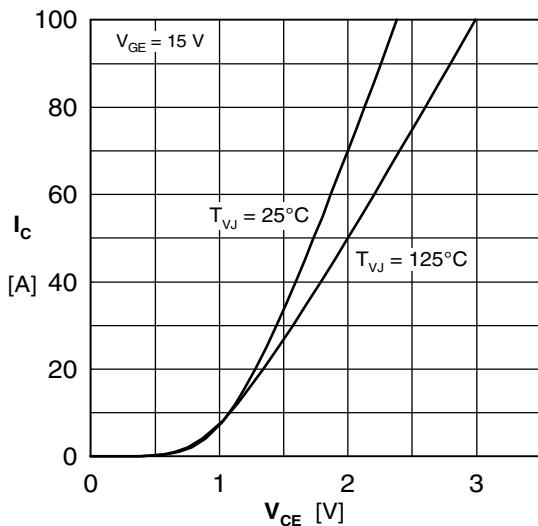
Inverter T1 - T6


Fig. 1 Typ. output characteristics

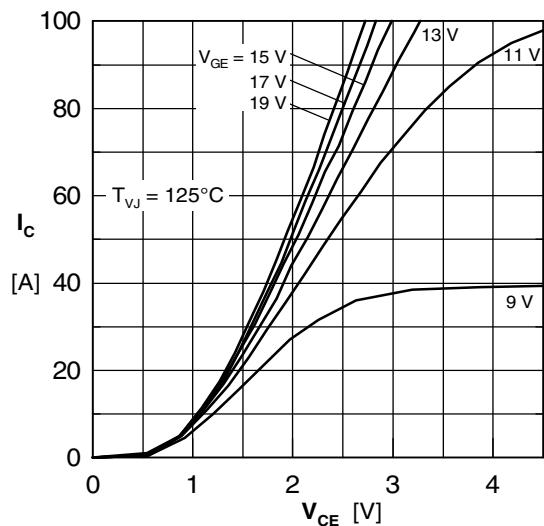


Fig. 2 Typ. output characteristics

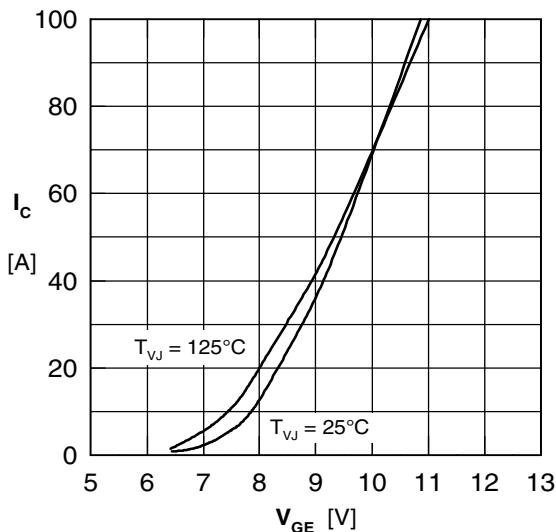


Fig. 3 Typ. tranfer characteristics

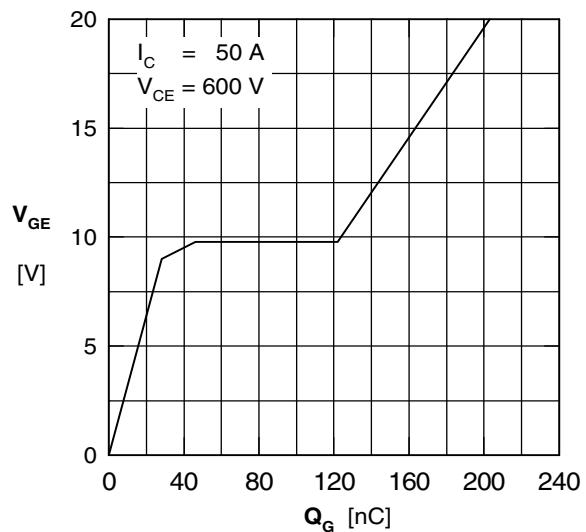


Fig. 4 Typ. turn-on gate charge

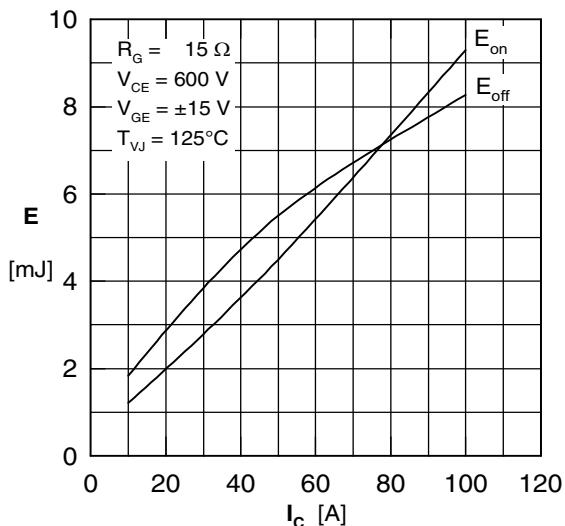


Fig. 5 Typ. switching energy vs. collector current

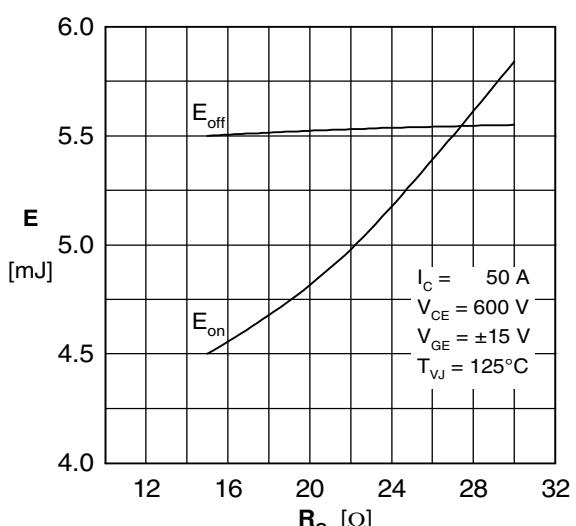
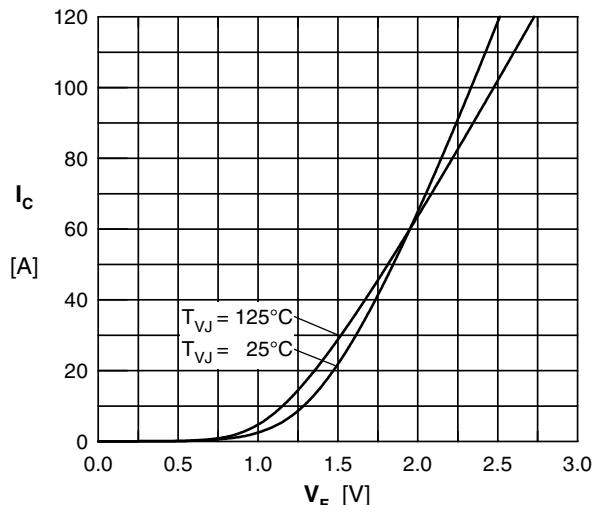
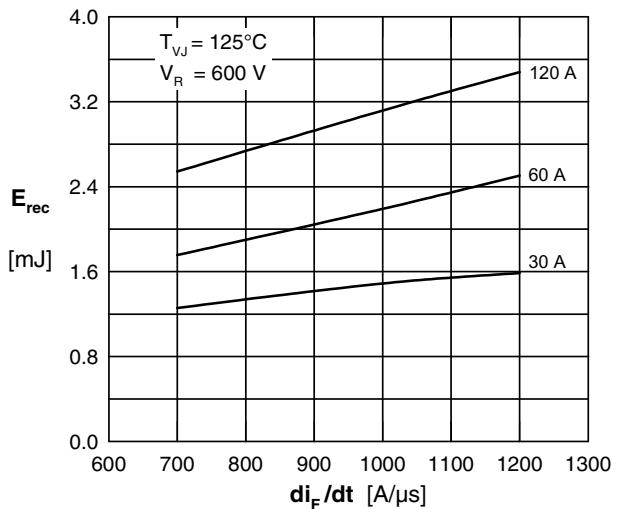


Fig. 6 Typ. switching energy vs. gate resistance

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Inverter D1 - D6

 Fig. 7 Typ. Forward current versus V_F

 Fig. 8 Typ. recovery energy E_{rec} versus di/dt

	IGBT		FRD	
	R_i	τ_i	R_i	τ_i
1	0.1	0.0025	0.137	0.0025
2	0.05	0.03	0.1	0.03
3	0.21	0.03	0.233	0.03
4	0.07	0.08	0.13	0.08

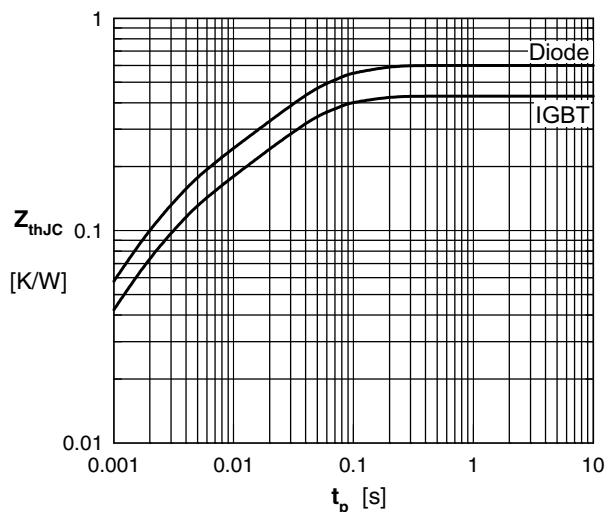


Fig. 9 Typ. transient thermal impedance